



The Center for Advanced Micro- and Nano-Optics located at the Fraunhofer IOF provides its customers a microstructure fabrication facility that meets the parameters otherwise only achievable in a semiconductor manufacturing plant. Covering the hole process chain of advanced optic development, the center is specialised in diffractive optics. Diffractive optics based on micro- and nanostructured surfaces offer flexible possibilities to present new optical functionality which are often barely achievable with conventional optics. This opens up new areas of application for optics.

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In collaboration with

 Institute of Applied Physics of the Friedrich-Schiller-University Jena



CENTER FOR ADVANCED MICRO- AND NANO-OPTICS



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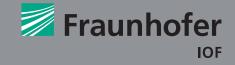
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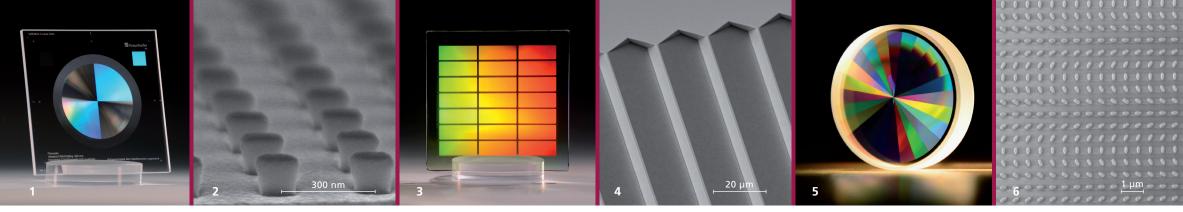
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FRAUNHOFER INSTITUTE FOR APPLIED OPTICS AND PRECISION ENGINEERING IOF

CMN-OPTICS

CENTER FOR ADVANCED MICRO- AND NANO-OPTICS



FULLY CUSTOMIZED OPTICAL ELEMENTS

From design to characterization to satisfy customer needs

- Optical elements design
- Technology consulting
- Adapted manufacturing technologies for customized element generation
- Integration of single components into complex systems (specific optical/mechanical design)
- Optical and structural characterization
- Assembling of prototypes
- Processing of optical elements and administration according to ISO 9001 standard



- 1 Effective-medium CGH for interferometric testing of aspheres
- 2 High resolution resist pattern
- 3 Transmission gratings
- 4 Echellette grating
- 5 Segmented quarter-wave plate
- 6 Metallic Nano-Wire array working as circular polarizer

TECHNOLOGY

Micro and nanostructuring

- Electron Beam Lithography System SB350 OS
- 300mm diameter writing capability
- Minimum feature size < 65 nm</p>
- Address grid 1 nm
- Placement accuracy < 15 nm</p>
- Advanced multilevel technology
- Efficient data processing capability

Accompanying technologies

- Planarization / IB and MR figuring of substrates
- Adhesive-free fused silica direct bonding
- Resist technology for 12" substrates
- Reactive ion etching
- Silicon, fused silica, high index materials
- Etching aspect ratio > 1:10
- Coating
- HR, AR, metals
- Atomic Layer Deposition (ALD)
- Sputtering, evaporation
- Wafer dicing and ultra precision machining
- Wafer scale replication

CHARACTERIZATION

- Scanning electron microscope
- Focused ion beam tooling
- Material analysis (EDX, EBSD)
- Atomic force microscope on 12" substrates
 - Height resolution 0.05 nm
- 12" plane-wave interferometer
 - 11" reference plane, WFE < 4 nm rms</p>
- Interference optical surface profiler
- Ellipsometer for layer stack characterization
- Measurement of optical function, e.g. efficiency, polarization sensitivity

APPLICATIONS

- Computer generated holograms (CGH)
- Diffraction gratings
- Beam splitters
- Sub-wavelength gratings, e.g. polarizer, wave-plates
- Highly efficient large scale pulse compression gratings
- Spectrometer gratings and GRISMs
- Photonic crystals

Selected references

- Effective medium grating for ESA GAIA mission
- NIR grating for ESA Sentinel 4 space mission
- Grating for Sentinel 5 Space Mission